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## Patent Abstracts of Japan

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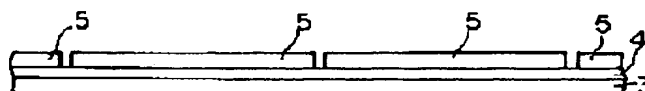
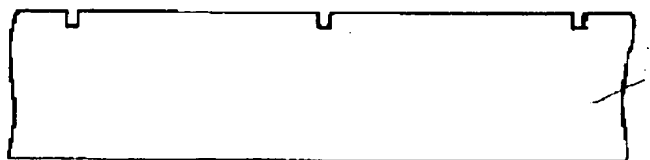
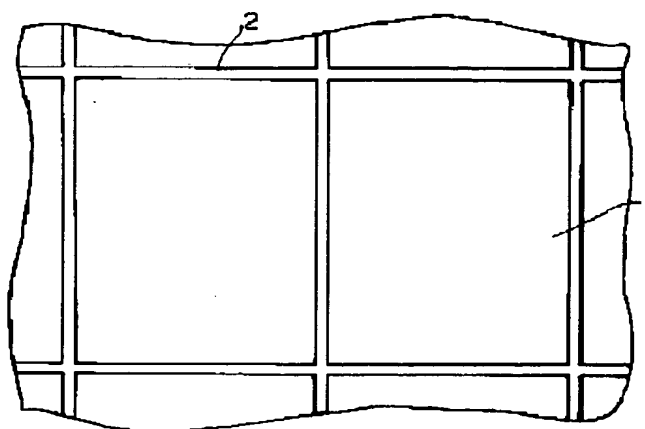
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H01L 21/68

TITLE : MANUFACTURE OF COLLET AND  
SEMICONDUCTOR DEVICE



ABSTRACT : PURPOSE: To facilitate the handling of a very thin chip and increase its reliability by applying a sheet to the active surface side of a semiconductor integrated circuit substrate and polishing the rear surface thereof.

CONSTITUTION: A cut groove 2 of a predetermined depth from the active surface side of a semiconductor substrate 1 is formed along the divided line of a semiconductor device on the surface of a semiconductor integrated circuit substrate (semiconductor substrate) 1. In addition, after a fixing sheet 3 is applied to the active surface side, the semiconductor substrate 1 is polished from the rear surface side up to the cut groove 2 in such manner that individually divided semiconductor integrated circuit chips are obtained. Furthermore, the application of the sheet 3 is performed through a ultraviolet hardening type adhesive. Even after divided, the sheet 3 remains in one body to protect the chips on the whole until they are separated from the sheet 3 to facilitate its handling.

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